

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): Method for molecular adhesion of a second electronic compound [[(6)]] on a first electronic compound [[(1)]], the contact surface of the first electronic compound [[(1)]] containing a polymer [[(4)]], comprising the coating, with a bonding layer [[(5)]], of at least some of the surface of the polymer [[(4)]] contained at the surface of the first electronic compound [[(1)]], with the molecular adhesion taking place between said bonding layer [[(5)]] and the second electronic compound [[(6)]].

Claim 2 (Currently Amended): Method according to claim 1 comprising the cleaning of the contact surface of the second electronic compound [[(6)]] and/or its coating with a layer [[(7)]] similar to the bonding layer [[(5)]].

Claim 3 (Currently Amended): Method according to ~~one of claims~~ claim 1 or 2, comprising the thinning of the second electronic compound [[(6)]] after adhesion thereof to the bonding layer [[(5)]].

Claim 4 (Currently Amended): Method according to ~~one of claims~~ claim 1 to 3, comprising the heat treatment of the assembly of the two compounds ~~(1, 6)~~ after adhesion.

Claim 5 (Currently Amended): Method according to ~~one of claims~~ claim 1 to 4, wherein the coating is produced by deposition of a bonding layer [[(5)]] having a thickness between 50 and 300 nm.

Claim 6 (Currently Amended): Method according to ~~one of claims~~ claim 1 to 5 comprising the polishing of the bonding layer [(5)] and/or its activation.

Claim 7 (Canceled).

Claim 8 (Currently Amended): Method according to ~~one of claims~~ claim 1 to 7 comprising the cross-linking of the polymer [(4)] prior to the coating thereof.

Claim 9 (Currently Amended): Method according to ~~one of the previous claims~~ claim 1, wherein the bonding layer [(5)] consists of silicon oxide.

Claim 10 (Currently Amended): Method for producing an array [(10)] of stacked electronic compounds [(1)] comprising the development of at least one first electronic compound [(1)] so that the surface of the first electronic compound at least partially consists of a polymer [(4)], and the adhesion on this surface of a second compound [(6)] according to the method defined in ~~one of claims~~ claim 1 to 9.

Claim 11 (Currently Amended): Three-dimensional array [(10)] of electronic compounds [(1)] comprising a plurality of interface layers [(5)], wherein each of the interface layers [(5)] is at least equal to the surface of the array [(10)] at the level of said interface layer [(5)], so that at least some of the interface layers [(5)] directly separate a polymer [(4)] from at least one electronic component [(3)].

Claim 12 (Currently Amended): Array according to claim 11, consisting of a stack of electronic compounds (1, 1'), wherein each compound [[(1)]] has the same shape and/or size as the adjacent compound [[(1')]] from which it is separated by an interface layer [[(5)]].

Claim 13 (Currently Amended): Array according to ~~one of claims~~ claim 11 or 12, wherein the interface layers [[(5)]] consist of silicon oxide, silicon nitride and/or silicon oxynitride.

Claim 14 (New): Method according to claim 1, wherein the coating is produced by deposition of a bonding layer made of silicon oxide having a thickness between 50 and 300 nm.

Claim 15 (New): Method according to claim 14 comprising the polishing and/or the activation of the silicon layer.

Claim 16 (New): Method according to claim 15 comprising the cross-linking of the polymer prior to the coating thereof.

Claim 17 (New): Method for producing an array of stacked electronic compounds comprising the development of at least one first electronic compound so that the surface of the first electronic compound at least partially consists of a polymer, and the adhesion on this surface of a second compound according to the method defined in claim 16.

Claim 18 (New): Method for molecular adhesion of a second electronic compound on a first electronic compound, the contact surface of the first electronic compound containing a

polymer, comprising the cross-linking of the polymer, the coating with silicon oxide, silicon nitride and/or silicon oxinitride, of at least some of the surface of the polymer contained at the surface of the first electronic compound, the polishing and/or activation of said silicon layer, with the molecular adhesion taking place between said silicon layer and the second electronic compound.

Claim 19 (New): Method according to claim 18 comprising the heat treatment of the assembly of the two compounds after adhesion.

Claim 20 (New): Method according to claim 19 comprising the thinning of the second electronic compound after adhesion thereof.